The 28th edition of the IEEE International
Interconnect Technology Conference

# IEEE IITC 2025

JUNE 2 / MON. ~ 5 / THU., 2025
THE WESTIN JOSUN BUSAN, BUSAN, KOREA

## Sponsorship Prospectus

**Organized by** 한국전기전자재료학회 The Korean Institute of Electrical and Electronic Material Engineers UNIST

**Sponsored by** IEEE ELECTRON DEVICES SOCIETY

# Conference Information

## Conference Title

The 28th edition of the IEEE International Interconnect Technology Conference (IEEE IITC 2025)

## Date

June 2 ~ 5, 2025

## Location

The Westin Josun Busan, Busan, Korea

## Organized by

The Korean Institute of Electrical and Electronic Material Engineers (KIEEME)
Ulsan National Institute of Science and Technology (UNIST)

## Website

https://iitc2025.org/index.php

# Organizing Committee

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## Program Chair

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| **Publicity Co-chair** | Se Hun Kwon (Pusan National University) |
| **Co-Treasurer** | Tae-Ik Lee (Korea Institute of Industrial Technology (KITECH)) |

# Important Dates

| | |
|---|---|
| · **Abstract Submission Deadline** | **Feb. 21, 2025, 23:59 / KST** |
| · **Notification of Acceptance** | **Apr. 1, 2025, 23:59 / KST** |
| · **Early Bird Registration** | **May. 15, 2025, 23:59 / KST** |

# Conference Topics

1. **Process integration, advanced patterning for MOL/BEOL**
2. **Materials and Unit Processes (Dielectrics, metals, barriers, Wet, CMP, PVD, CVD, ALD, Selective deposition/SAMs, patterning, advanced cleaning and surface treatment)**
3. **Reliability and Failure analysis, characterization, techniques, and methods**
4. **Advanced material/process characterization, system technology & design-technology co-optimization, and modelling techniques**
5. **Advanced packaging for 2.5D/3D, Monolithic 3D IC, hybrid bonding**

# Program at a Glance

| Jun. 2 (Mon.) | Jun. 3 (Tue.) ~ 5 (Thu.) |
|---|---|
| Workshop | Conference |

# About the Sponsorship

The IEEE IITC 2025 is sponsored by the IEEE Electron Devices Society as the premier conference for interconnect technology devoted to leading-edge research in the field of advanced metallization and 3D integration for ULSI applications. As our conference draws submissions and attendees from around the globe, including experts and influencers from all steps along the industry value chain, becoming a sponsor will significantly increase your company’s visibility to conference attendees representing industry, academia, and national laboratories in semiconductor processing, interconnect design, and equipment development. Sponsorship helps us ensure that the IEEE IITC 2025 draws reports of the highest quality and most timely, relevant findings for this audience.

Sponsorships are available for certain items and events (listed below). In addition to the levels and benefits listed below, all sponsors will be announced and thanked on the slides at the beginning of the technical sessions; appear in the IITC published program and appear on the IITC web page.

# Sponsorship Guidelines

Please fill out the Sponsorship Application Form and fax or e-mail it to the IEEE IITC 2025 Secretariat. (info@iitc2025.org)

# Sponsorship Application Deadline

**April 11, 2025**

# Cancellation Policy

- **Before April 11, 2025:** 100% of full payment will be refunded.
- **From April 11, 2025:** Payment will not be refunded.
- Cancellation of sponsorship must be made in written format to the secretariat via e-mail.

# Sponsorship Packages

| **Sponsorship Benefits** | **Platinum** | **Gold** | **Silver** | **Bronze** |
|---|---|---|---|---|
| | USD 15,000 | USD 8,000 | USD 6,000 | USD 3,000 |
| USD 1 = KRW 1,450 | KRW 21,750,000 | KRW 11,600,000 | KRW 8,700,000 | KRW 4,350,000 |
| Exhibition booth for company promotion | √ | √ | √ | √ |
| Sponsorship acknowledgement at opening session | √ | √ | √ | √ |
| Sponsorship sign included in the announcement during conference | √ | √ | √ | √ |
| Display of your company logo on the website and hyperlinked to your company website or promotion video | √ | √ | √ | √ |
| Complimentary registrations to the technical sessions | 4 | 2 | 1 | |
| Broadcasting 5-min promotion video or presentation during conference period | √ | √ | | |
| Dedicated sponsor of special event | √ | | | |

***Platinum-level is strictly limited to 1 sponsor on a first-come, first-serve basis.**

# Sponsorship Application Form

## A. Company Information

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|---|---|---|---|
| **Company Name** | | | |
| **Address** | | | |
| **Website** | | | |
| **President** | | | |
| **Contact Person Name** | | **Job Title/ Department** | |
| **Telephone** | | **Mobile** | |
| **E-mail** | | | |

## B. Sponsorship Application (Please check(V) for your choice)

***USD 1 = KRW 1,450**

| | | |
|---|---|---|
| Category | ☐ **Platinum** | **USD 15,000 / KRW 21,750,000** |
| | ☐ **Gold** | **USD 8,000 / KRW 11,600,000** |
| | ☐ **Silver** | **USD 6,000 / KRW 8,700,000** |
| | ☐ **Bronze** | **USD 3,000 / KRW 4,350,000** |

## C. Payment Method (Wire Transfer Only)

***Only for domestic**

- **Account Holder:** The Korean Institute of Electrical and Electronic Material Engineers (KIEEME)
- **Account Number:** 0602-0605-2025
- **Bank Name:** SUHYUP BANK
- **SWIFT Code:** NFFCKRSE
- **Bank Address:** 22 Teheran-ro 7-gil, Gangnam-gu, Seoul, South Korea

***Only for overseas**

- **Account Holder:** The Korean Institute of Electrical and Electronic Material Engineers (KIEEME)
- **Account Number:** 1800-0066-9680
- **Bank Name:** Suhyup bank
- **SWIFT Code:** NFFCKRSEXXX
- **Bank Address:** The Korean federation of Science and Technology Branch. 22, Teheran-ro 7-gil, Gangnam-gu, Seoul, Republic of Korea.

- **Sponsorship Application Deadline: April 11, 2025**
- Please fill out and fax or e-mail the Sponsorship Application form to the IEEE IITC 2025 Secretariat.

**Name of Applicant:** ____________________ **Date:** __________________

**Signature:** __________________

**IEEE IITC 2025 Secretariat**
E-mail: info@iitc2025.org / Tel: +82-42-472-7460 / Fax: +82-42-472-7459